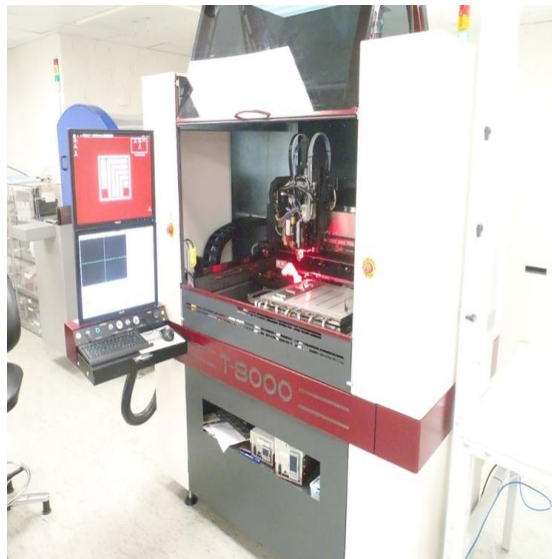


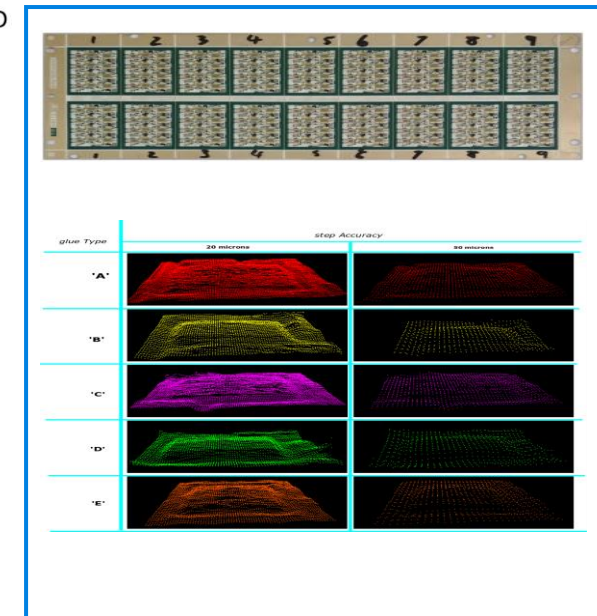
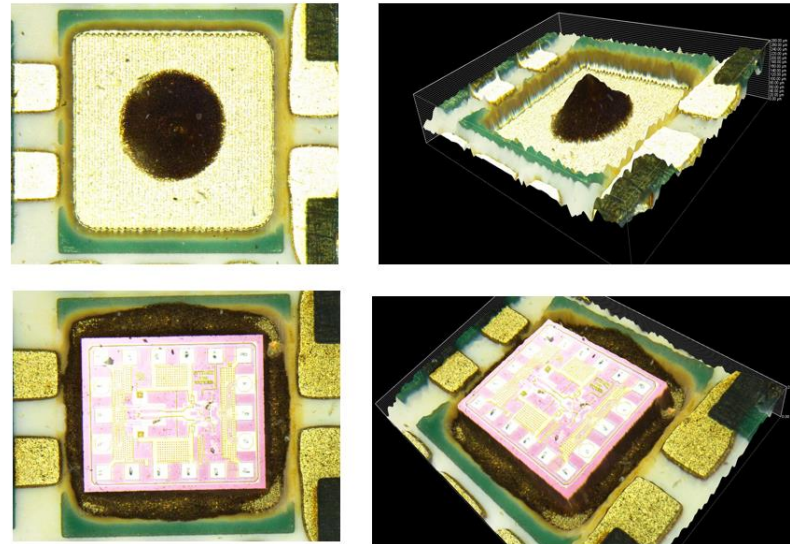
# Microsemi Semiconductor Manufacturer

- ❖ Microsemi assembles PCBs for different business.
- ❖ The assembly process consists of dispensing conductive glue on a Liquid Crystal Polymer (LCP) substrate with tight design specifications.
- ❖ Microelectronic components need to be precisely positioned on the wafer using Tresky machine.
- ❖ The components are attached to a LCP substrate by means of a conductive glue dispensed.
- ❖ Once the glue dots have been placed on the substrate the bond head then picks up the silicon die from a waffle tray and places it into the glue to a controlled height.



Tresky Die Placer

- The following images show a single glue dot and the die after placement in 2D and 3D.



A PCB including the glue images